



Material Content Data Sheet



Sales Product Name		BTT6050-2EKA		Issued		29. August 2013		
MA#		MA001026374						
Package		PG-DSO-14-40		Weight*		149.96 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.421	2.28	2.28	22814	22814
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		116	
	non noble metal	zinc	7440-66-6	0.070	0.05		464	
	non noble metal	iron	7439-89-6	1.392	0.93		9281	
wire	non noble metal	copper	7440-50-8	56.512	37.69	38.68	376851	386712
	non noble metal	copper	7440-50-8	1.078	0.72	0.72	7189	7189
	encapsulation	organic material	carbon black	1333-86-4	0.168	0.11		1117
plastics	plastics	epoxy resin	-	7.707	5.14		51396	
	inorganic material	silicondioxide	60676-86-0	75.900	50.60	55.85	506142	558655
leadfinish	non noble metal	tin	7440-31-5	1.226	0.82	0.82	8177	8177
plating	noble metal	silver	7440-22-4	1.417	0.95	0.95	9453	9453
glue	plastics	epoxy resin	-	0.184	0.12		1225	
	noble metal	silver	7440-22-4	0.866	0.58	0.70	5775	7000
*deviation	< 10%		Sum in total:			100,00		1000000

Important Remarks:

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